

Single-Output LDO Regulators

35V Voltage Resistance

1A LDO Regulators

BDxxFC0WEFJ series

●Description

The BDxxFC0WEFJ series are low-saturation regulators. The series' output voltages are Variable, 3.0V, 3.3V, 5.0V, 6.0V, 7.0V, 8.0V, 9.0V, 10.0V, 12.0V, and 15.0V and package is HTSOP-J8. This series has a built-in over-current protection circuit that prevents the destruction of the IC due to output short circuits and a thermal shutdown circuit that protects the IC from thermal damage due to overloading.

●Key Specifications

- 1) Output current capability: 1A
- 2) Output voltage: Variable, 3.0V, 3.3V, 5.0V, 6.0V, 7.0V, 8.0V, 9.0V, 10.0V, 12.0V, and 15.0V
- 3) High output voltage accuracy (Ta=25°C): ±1%
- 4) Low saturation with PDMOS output
- 5) Built-in over-current protection circuit that prevents the destruction of the IC due to output short circuits
- 6) Built-in thermal shutdown circuit for protecting the IC from thermal damage due to overloading
- 7) Low ESR Capacitor
- 8) HTSOP-J8 package

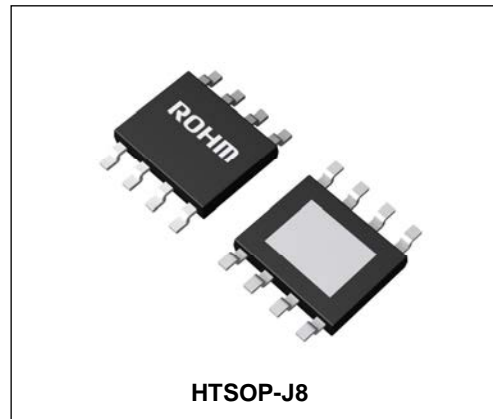
●Features

- Supply Voltage(V_{OUT} ≥ 3.0V): V_{OUT}+1.0V to 26.5V
- Supply Voltage(V_{OUT} < 3.0V): 4.0V to 26.5V
- Output Voltage(BD00FC0WEFJ): 1.0V to 15.0V
- Output Current: 1A
- Output Voltage Precision(Ta=25°C): ±1%
- Operating Temperature Range: -25°C ≤ Ta ≤ +85°C

●Package

HTSOP-J8

(Typ.) (Typ.) (Max.)
 4.90mm x 6.00mm x 1.00mm



●Ordering part number

B D x x F C 0 W E F J						-	E 2
Part Number	Output voltage	Input Voltage	Output Current	Shutdown Mode	Package		Packaging and forming specification
	00: Variable						
	30: 3.0V	F:35V	C0:1.0A	"W": Included	EFJ : HTSOP-J8		E2: Emboss tape reel
	33: 3.3V						
	50: 5.0V						
	60: 6.0V						
	70: 7.0V						
	80: 8.0V						
	90: 9.0V						
	J0: 10.0V						
	J2: 12.0V						
	J5: 15.0V						

● Typical Application Circuits

〈Output Voltage Variable Type〉

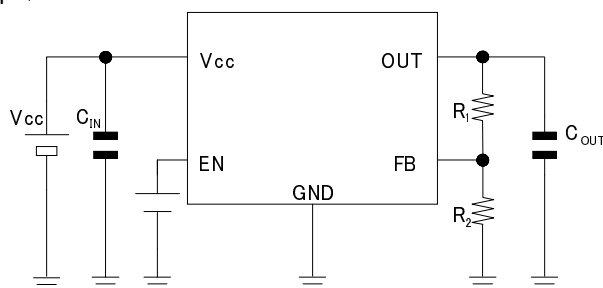


Figure 1. Typical Application Circuits
Output Voltage Variable Type

〈Output Voltage Fixed Type〉

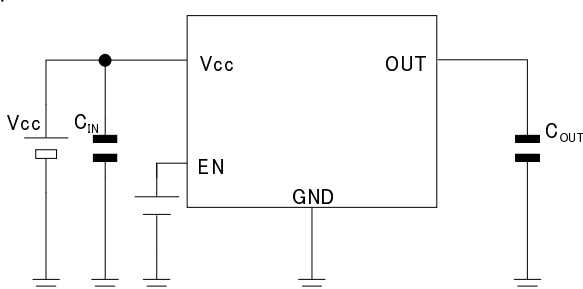


Figure 2. Typical Application Circuits
Output Voltage Fixed Type

● Pin Configuration/Pin Description

〈HTSOP-J8〉

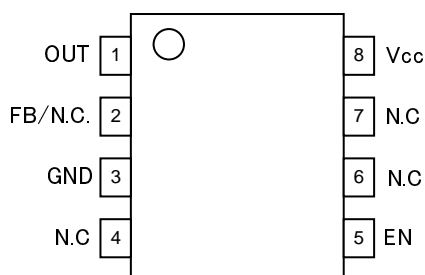


Figure 3. Pin Configuration

Pin No.	Pin name	Pin Function
1	OUT	Output pin
2	FB /N.C.	Feedback pin (BD00FC0WEFJ) No Connection (BDxxFC0WEFJ)
3	GND	GND pin
4	N.C.	No Connection (Connect to GND or leave OPEN)
5	EN	Enable pin
6	N.C.	No Connection (Connect to GND or leave OPEN)
7	N.C.	No Connection (Connect to GND or leave OPEN)
8	V _{CC}	Input pin
Reverse	GND	Substrate(Connect to GND)

※N.C. Pin can be open, because it is not connected to the IC.

●Block diagrams

〈BD00FC0WEFJ (Output Voltage Variable Type)〉

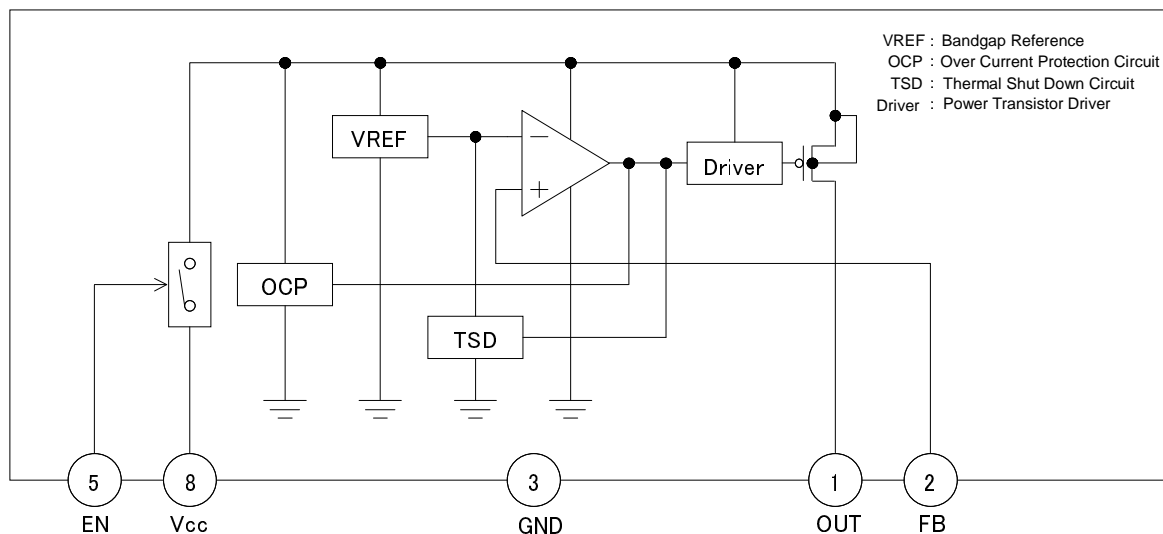


Figure 4. Block diagrams
 BD00FC0WEFJ (Output Voltage Variable Type)

〈BDxxFC0WEFJ (Output Voltage Fixed Type)〉

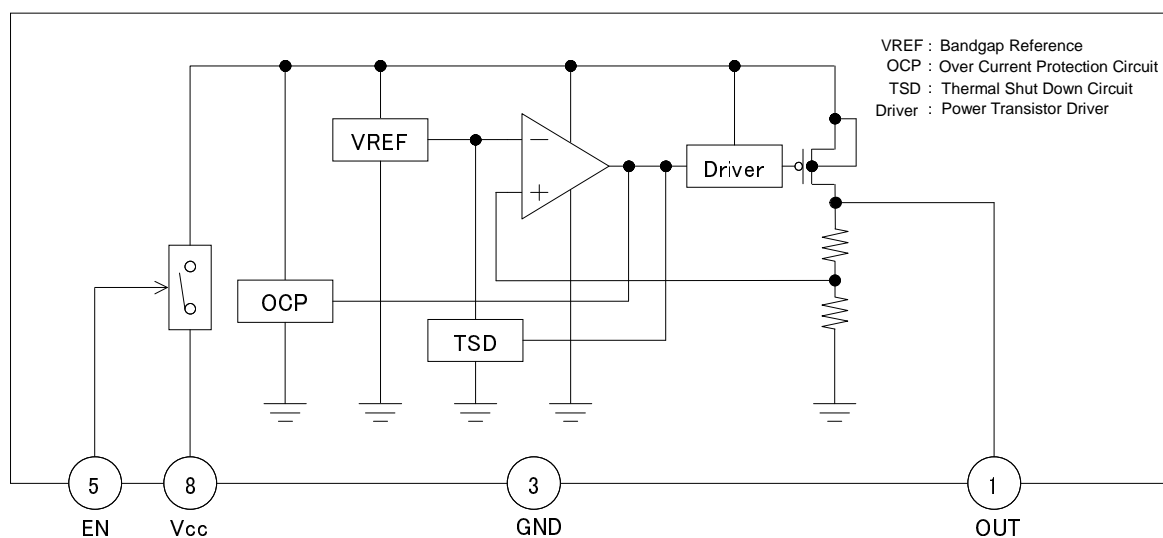


Figure 5. Block diagrams
 BDxxFC0WEFJ (Output Voltage Fixed Type)

● Absolute Maximum Ratings (Ta= 25°C)

Parameter	Symbol	Ratings	Unit
Supply Voltage ※1	V _{CC}	-0.3 to +35.0	V
EN Voltage ※2	V _{EN}	-0.3 to +35.0	V
Power Dissipation	P _d	2110 ※3	mW
Operating Temperature Range	T _{opr}	-25 to +85	°C
Storage Temperature Range	T _{stg}	-55 to +150	°C
Maximum Junction Temperature	T _{jmax}	150	°C

※1 Do not exceed P_d.

※2 The order of starting up power supply (V_{CC}) and EN pin does not have a problem, provided that they are operated within the power supply voltage range.

※3 Reduced by 16.9mW/°C for temperature above 25°C. (When mounted on a two-layer glass epoxy board 70mm × 70mm × 1.6mm dimension)

NOTE : This product is not designed for protection against radioactive rays.

● Operating Conditions (-25°C ≤ Ta ≤ +85°C)

Parameter	Symbol	Min.	Max.	Unit
Supply Voltage (V _{OUT} ≥ 3.0V)	V _{CC}	V _{OUT} +1	26.5	V
Supply Voltage (V _{OUT} < 3.0V)	V _{CC}	4.0	26.5	V
Startup Voltage (I _{OUT} =0mA)	V _{CC}	-	3.8	V
EN Voltage	V _{EN}	0	26.5	V
Output Current	I _{OUT}	0	1.0	A
Output Voltage ※4 (BD00FC0WEFJ)	V _{OUT}	1.0	15.0	V

※4 Please refer to Notes when using BD00FC0WEFJ at output voltage of 1.0V to 3.0V.

● Electrical Characteristics

Unless otherwise specified, Ta=25°C, V_{CC}=13.5V, I_{OUT}=0mA, V_{EN}=5.0V

The resistor between FB and OUT =56.7kΩ, FB and GND =10kΩ (BD00FC0WEFJ)

Parameter	Symbol	Guaranteed Limit			Unit	Conditions
		Min.	Typ.	Max.		
Circuit Current at shutdown mode	I _{SD}	-	0	5	μA	
Circuit Current	I _{CC}	-	0.5	2.5	mA	
Output Reference Voltage (BD00FC0WEFJ)	V _{FB}	0.742	0.750	0.758	V	I _{OUT} =50mA
Output Voltage	V _{OUT}	V _{OUT} ×0.99	V _{OUT}	V _{OUT} ×1.01	V	I _{OUT} =500mA
Minimum dropout voltage	V _{CO}	-	0.3	0.5	V	V _{CC} = V _{OUT} ×0.95, I _{OUT} =500mA
Line Regulation	Reg.I	-	20	80	mV	V _{OUT} +1.0V→26.5V
Load Regulation	Reg.I _{OUT}	-	V _{OUT} ×0.010	V _{OUT} ×0.020	V	I _{OUT} =5mA→1A
EN High Voltage	V _{EN} (High)	2.0	—	—	V	ACTIVE MODE
EN Low Voltage	V _{EN} (Low)	—	—	0.8	V	OFF MODE
EN Bias Current	I _{EN}	—	25	50	μA	

Reference Data

BD00FC0WEFJ series (5.0V Output Setting)

Unless otherwise specified, $T_a=25^\circ\text{C}$, $V_{CC}=13.5\text{V}$, $V_{EN}=5.0\text{V}$, $I_{OUT}=0\text{mA}$, $V_{OUT}=5.0\text{V}$
(The resistor between FB and OUT = $56.7\text{k}\Omega$, FB and GND = $10\text{k}\Omega$)

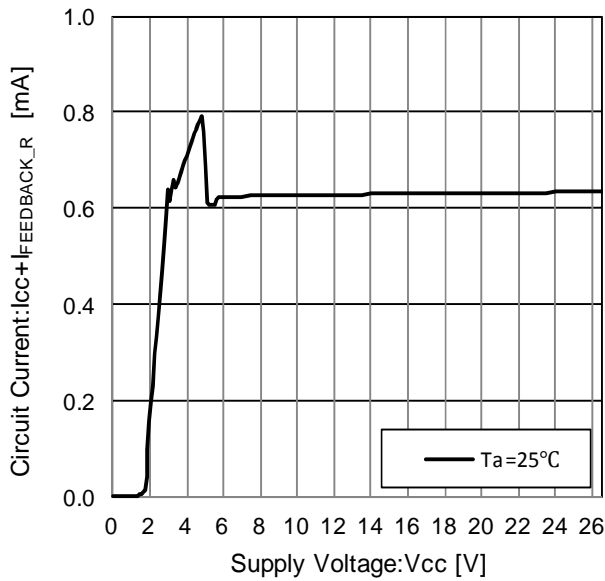


Figure 6. Circuit Current
($I_{FEEDBACK_R} \approx 75\mu\text{A}$)

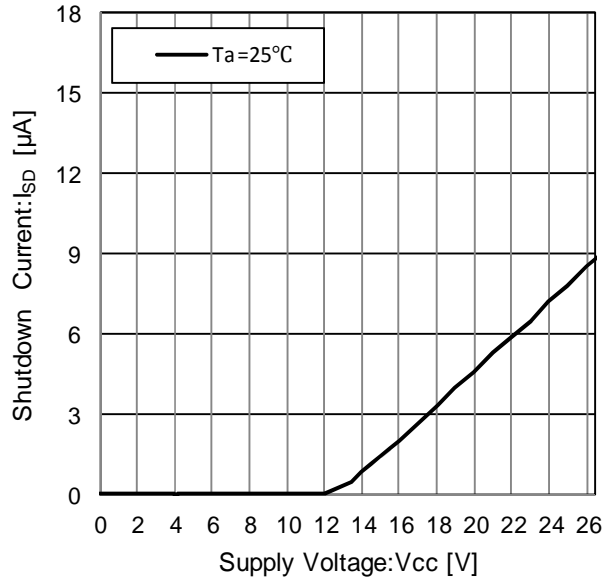


Figure 7. Shutdown Current

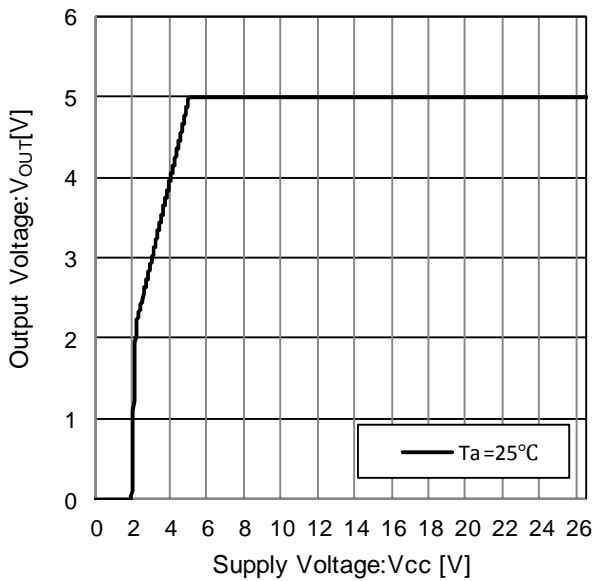


Figure 8. Line Regulation
($I_{OUT}=0\text{mA}$)

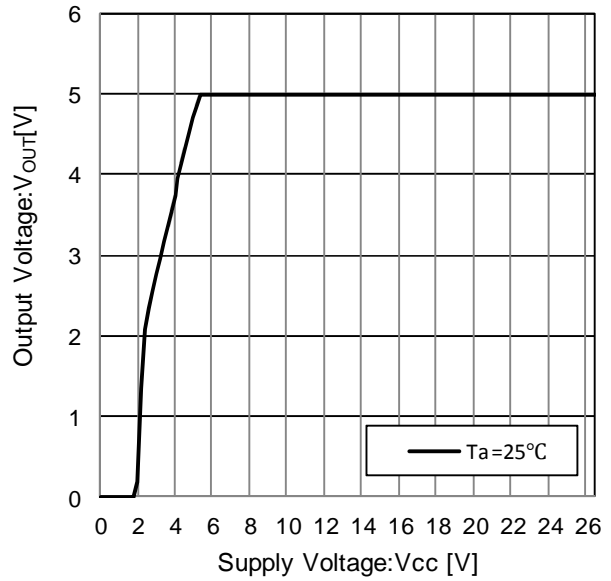


Figure 9. Line Regulation
($I_{OUT}=500\text{mA}$)

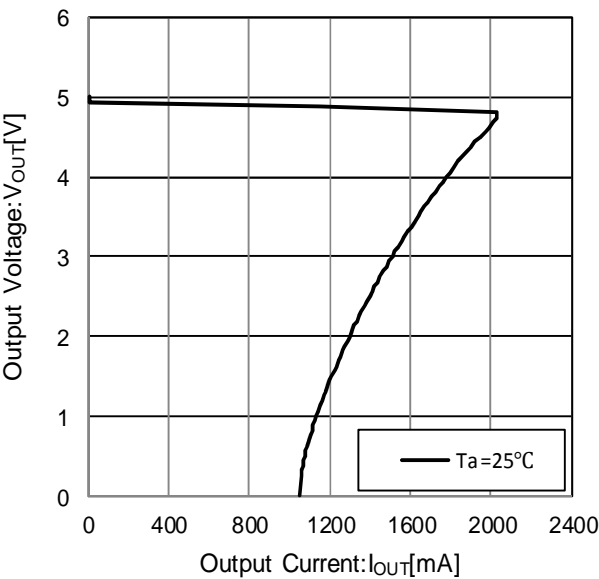


Figure 10. Load Regulation

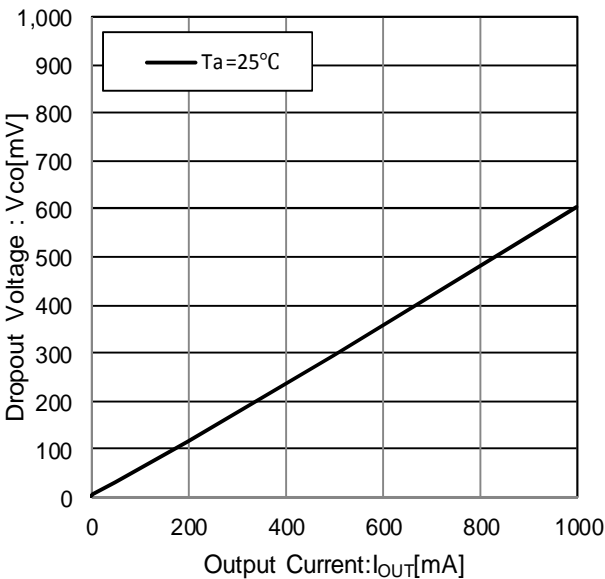


Figure 11. Dropout Voltage
($V_{CC}=4.75\text{V}$)
($I_{OUT}=0\text{mA} \rightarrow 1000\text{mA}$)

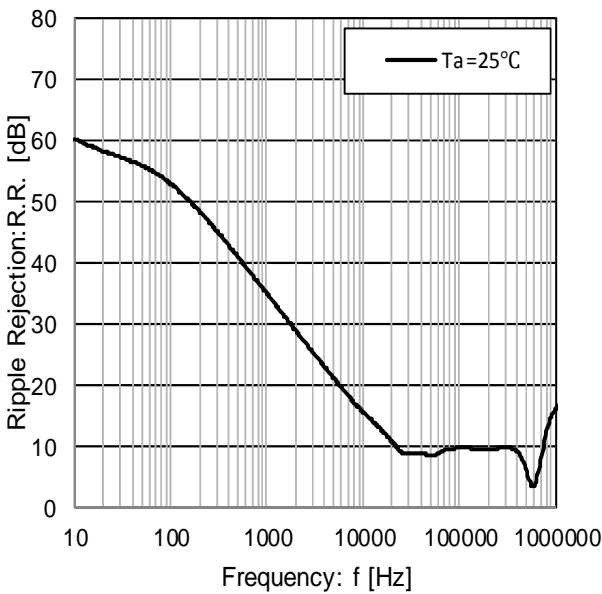


Figure 12. Ripple Rejection
($I_{OUT} = 100\text{mA}$)

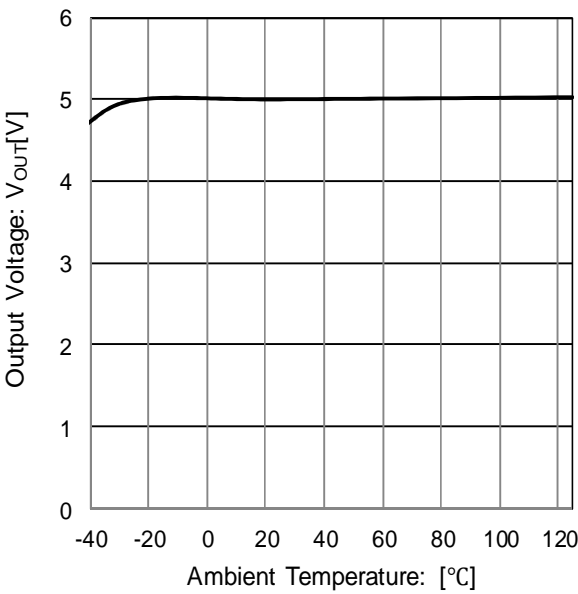


Figure 13. Output Voltage
Temperature Characteristic

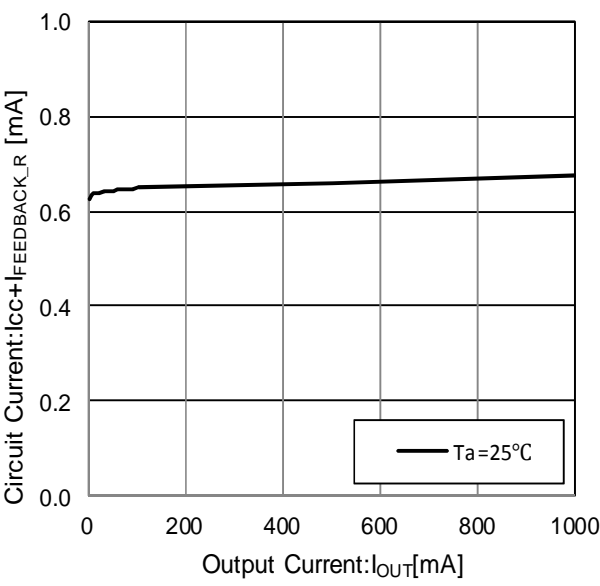


Figure 14. Circuit Current
($I_{OUT} = 0\text{mA} \rightarrow 1000\text{ mA}$)
($I_{FEEDBACK_R} \approx 75\mu\text{A}$)

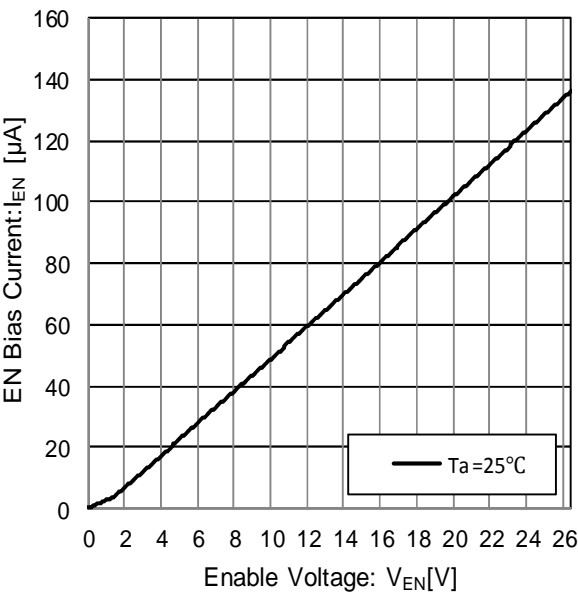


Figure 15. EN Voltage vs EN Current

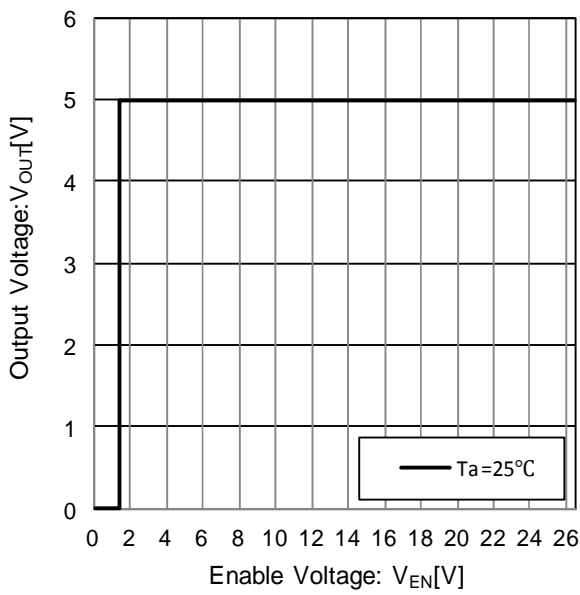


Figure 16. EN Voltage vs Output Voltage

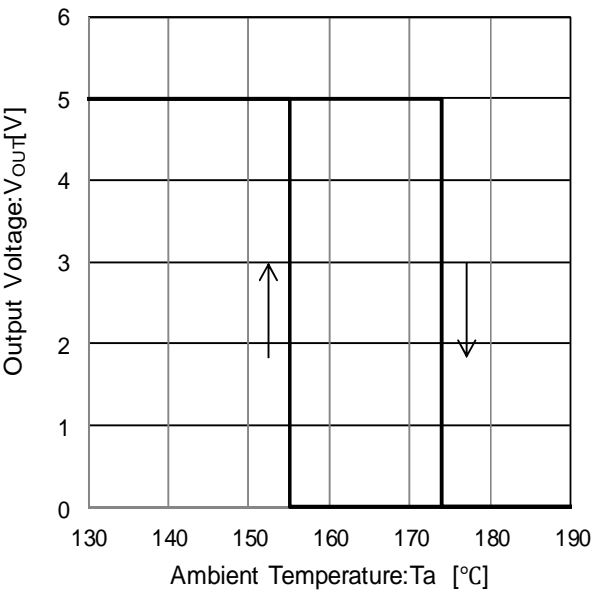
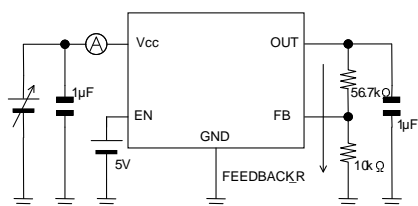


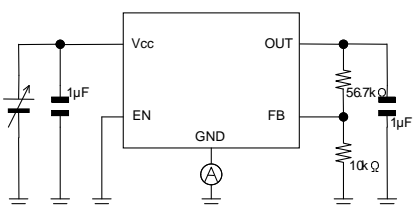
Figure 17. Thermal Shutdown
Circuit Characteristic

● Measurement setup for reference data

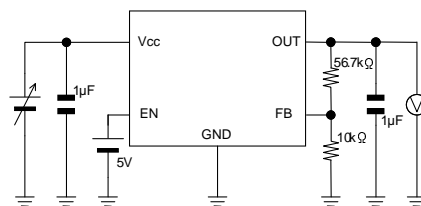
■ BD00FC0WEFJ series (5.0V Output Setting)



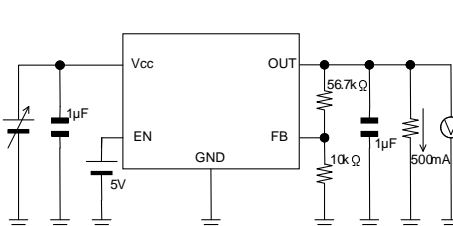
Measurement setup for Figure 6



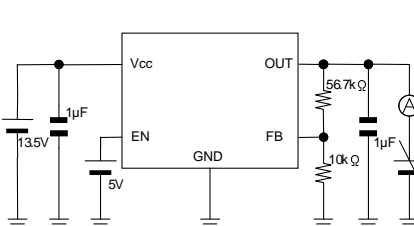
Measurement setup for Figure 7



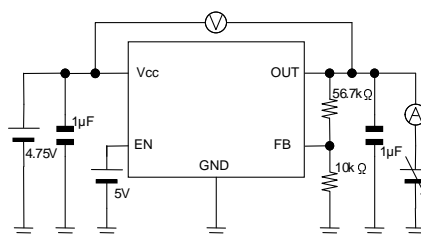
Measurement setup for Figure 8



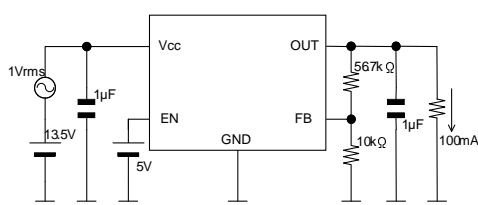
Measurement setup for Figure 9



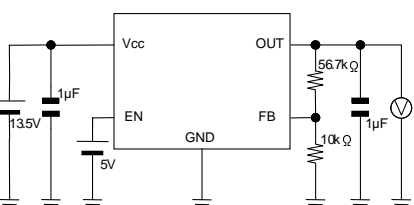
Measurement setup for Figure 10



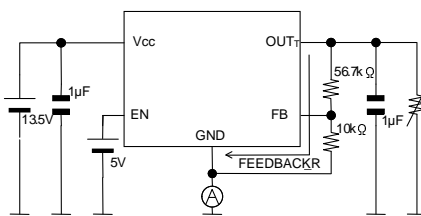
Measurement setup for Figure 11



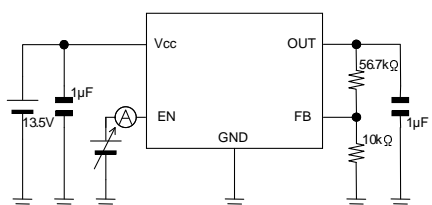
Measurement setup for Figure 12



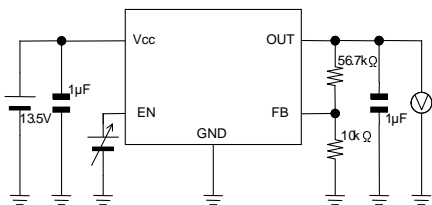
Measurement setup for Figure 13



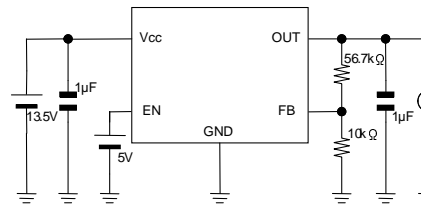
Measurement setup for Figure 14



Measurement setup for Figure 15



Measurement setup for Figure 16



Measurement setup for Figure 17

● Application Examples

- Applying positive surge to the Vcc pin

If there is a possibility that surges higher than 35.0V will be applied to the Vcc pin, a zener diode should be placed between the Vcc pin and GND pin, as shown in the Figure below.

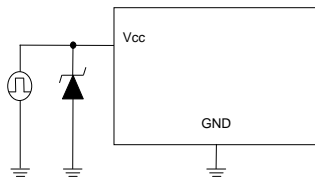


Figure 18.

- Applying negative surge to the Vcc pin

If there is a possibility that negative surges lower than the GND are applied to the Vcc pin, a schottky diode should be placed between the Vcc pin and GND pin, as shown in the Figure below.

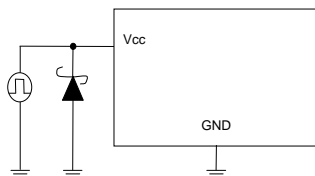


Figure 19.

- Implementing a protection diode

If there is a possibility that a large inductive load is connected to the output pin resulting in back-EMF at time of startup and Shutdown, a protection diode should be placed as shown in the Figure below.

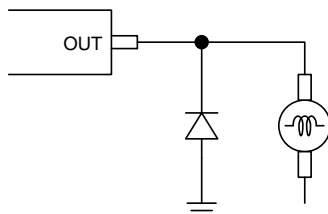
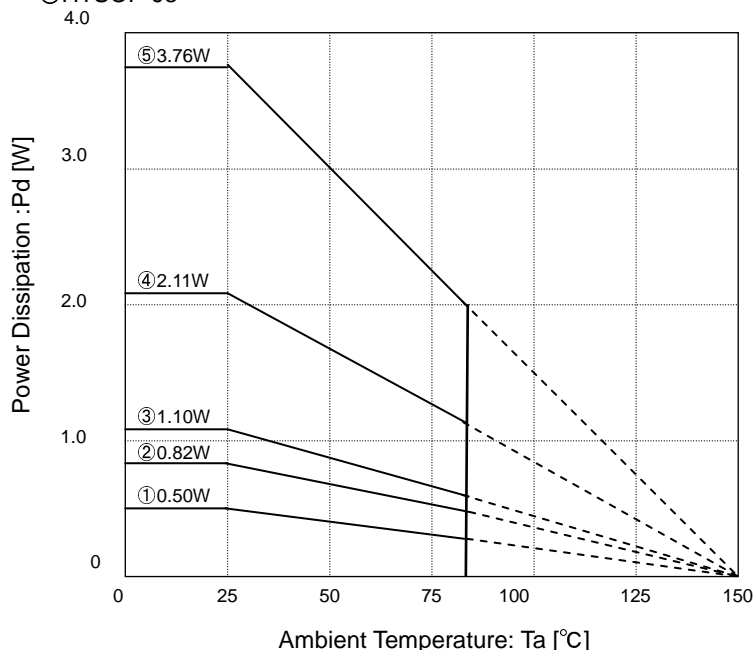


Figure 20.

Thermal Design

HTSOP-J8



Measurement condition: mounted on a ROHM board

PCB size: 70mm × 70mm × 1.6mm
(PCB with thermal via)

• Solder the thermal pad to Ground

- ① IC only
θj-a=249.5°C/W
- ② 1-layer (copper foil : 0mm × 0mm)
θj-a=153.2°C/W
- ③ 2-layer (copper foil : 15mm × 15mm)
θj-a=113.6°C/W
- ④ 2-layer (copper foil : 70mm × 70mm)
θj-a=59.2°C/W
- ⑤ 4-layer (copper foil : 70mm × 70mm)
θj-a=33.3°C/W

As the power consumption increases above the maximum allowable power dissipation of the chip, the temperature across the chip also increases. When considering thermal design for the regulator, operation should be maintained within the following conditions:

1. Ambient temperature Ta can be not higher than 85°C.
2. Chip junction temperature (Tj) can be not higher than 150°C.

Chip junction temperature can be determined as follows:

Calculation based on ambient temperature (Ta)

$$T_j = T_a + \theta_{j-a} \times W$$

< Reference values >

θj-a: HTSOP-J8	153.2°C/W	1-layer PCB (copper foil density 0mm × 0mm)
	113.6°C/W	2-layer PCB (copper foil density 15mm × 15mm)
	59.2°C/W	2-layer PCB (copper foil density 70mm × 70mm)
	33.3°C/W	4-layer PCB (copper foil density 70mm × 70mm)
PCB size: 70mm × 70mm × 1.6mm (PCB with thermal via)		

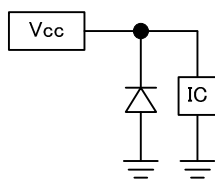
Most of the heat loss that occurs in the BDxxFC0WEFJ series is generated from the output Pch FET. Power loss is determined by the voltage drop across V_{CC}-OUT and the output current. Be sure to confirm the system's input and output voltages, as well as the output current conditions in relation to the power dissipation characteristics of the V_{CC} and V_{OUT} in the design. Bearing in mind that the power dissipation may vary substantially depending on the PCB employed, it is important to consider PCB size based on thermal design and power dissipation characteristics of the chip with the PCB.

$$\text{Power consumption [W]} = \{ \text{Input voltage (V}_{CC}) - \text{Output voltage (V}_{OUT}) \} \times I_{OUT} (\text{Average})$$

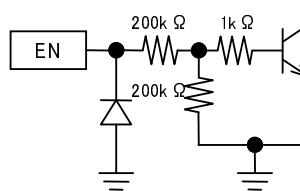
Example: Where V_{CC}=5.0V, V_{OUT}=3.3V, I_{OUT} (Average) = 0.1A,

$$\begin{aligned} \text{Power consumption [W]} &= \{ 5.0V - 3.3V \} \times 0.1A \\ &= 0.17W \end{aligned}$$

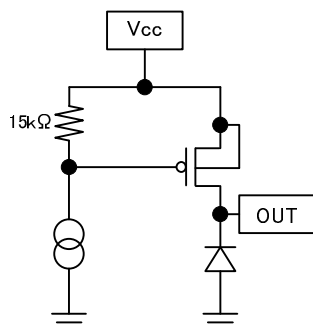
● I/O equivalent circuit

V_{CC} terminal

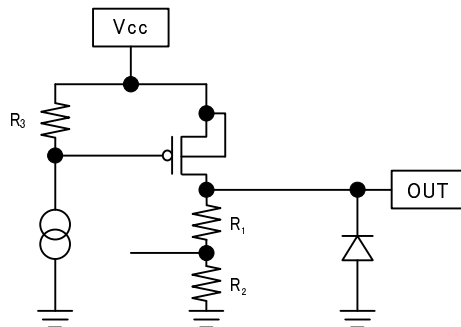
EN terminal

V_{OUT} terminal

(BD00FC0WEFJ)



(BDxxFC0WEFJ)



FB terminal

(BD00FC0WEFJ)

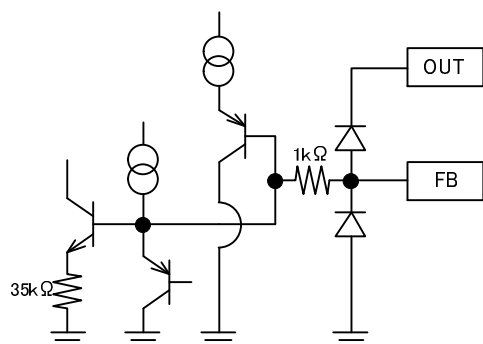


Figure 21.

● Output Voltage Configuration Method (BD00FC0WEFJ)

Please connect resistors R₁ and R₂ (which determines the output voltage) as shown in Figure 22.

Please be aware that the offset, due to the current that flows from the FB terminal, becomes large when resistors with large values are used. Resistance values ranging from R₂=5kΩ to 10kΩ is recommended.

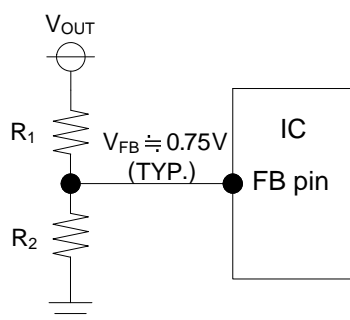


Figure 22.

V_{OUT} setting equation is,

$$V_{OUT} \doteq V_{FB} \times (R_1 + R_2) / R_2$$

Thoroughly check the constant settings on the application because circuit current increases depending on connected resistor.

Resistance value of R₂ is from 5kΩ to 10kΩ.
Determine R₁ by adjusting with R₂.

●Operational Notes

1. Absolute maximum ratings
Use of the IC in excess of absolute maximum ratings (such as the input voltage or operating temperature range) may result in damage to the IC. Assumptions should not be made regarding the state of the IC (e.g., short mode or open mode) when such damage is suffered. If operational values are expected to exceed the maximum ratings for the device, consider adding protective circuitry (such as fuses) to eliminate the risk of damaging the IC.
2. Electrical characteristics described in these specifications may vary, depending on temperature, supply voltage, external circuits, and other conditions. Therefore, be sure to check all relevant factors, including transient characteristics.
3. GND potential
The potential of the GND pin must be the minimum potential in the system in all operating conditions. Ensure that no pins are at a voltage below the GND at any time, regardless of transient characteristics.
4. Ground wiring pattern
When using both small-signal and large-current GND traces, the two ground traces should be routed separately but connected to a single ground potential within the application in order to avoid variations in the small-signal ground caused by large currents. Also, ensure that the GND traces of external components do not cause variations on GND voltage. The power supply and ground lines must be as short and thick as possible to reduce line impedance.
5. Inter-pin shorts and mounting errors
Use caution when orienting and positioning the IC for mounting on printed circuit boards. Improper mounting may result in damage to the IC. Shorts between output pins or between output pins and the power supply or GND pins (caused by poor soldering or foreign objects) may result in damage to the IC.
6. Operation in strong electromagnetic fields
Using this product in strong electromagnetic fields may cause IC malfunction. Caution should be exercised in applications where strong electromagnetic fields may be present.
7. Testing on application boards
When testing the IC on an application board, connecting a capacitor directly to a low-impedance pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from a jig or fixture during the evaluation process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.
8. Power Dissipation Pd
Using the unit in excess of the rated power dissipation may cause deterioration in electrical characteristics including reduced current capability due to the rise of chip temperature. The mentioned power dissipation in the absolute maximum rating of this specification, at HTSOP-J8 package when 70mm × 70mm × 1.6mm glass epoxy board is mounted, is the value of when there is no heat dissipation board. And in case this exceeds, take the measures like enlarge the size of board; make copper foil area for heat dissipation big; and use dissipation board and do not exceed the power dissipation.
9. Thermal consideration
Use a thermal design that allows for a sufficient margin in light of the Pd in actual operating conditions. Consider Pc that does not exceed Pd in actual operating conditions. ($P_d \geq P_c$)

T_{jmax} : Maximum junction temperature=150(°C) , T_a : Peripheral temperature(°C) ,
 θ_{ja} : Thermal resistance of package-ambience(°C/W), P_d : Package Power dissipation (W),
 P_c : Power consumption (W), V_{cc} : Input Voltage, V_{OUT} : Output Voltage, I_{OUT} : Load, I_{cc} : Circuit Current

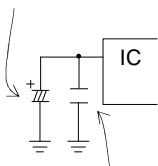
Package Power dissipation : $P_d (W) = (T_{jmax} - T_a) / \theta_{ja}$

Power consumption : $P_c (W) = (V_{cc} - V_{OUT}) \times I_{OUT} + V_{cc} \times I_{cc}$

10. Vcc pin

Insert a capacitor ($V_{OUT} \geq 5.0V$: capacitor $\geq 1\mu F$, $1.0V \leq V_{OUT} < 5.0V$: capacitor $\geq 2.2\mu F$) between the Vcc and GND pins. Choose the capacitance according to the line between the power smoothing circuit and the VCC pin. Selection of the capacitance also depends on the application. Verify the application and allow for sufficient margins in the design. It is recommended to use a capacitor with excellent voltage and temperature characteristics.

Electric capacitor



Ceramic capacitor, Low ESR capacitor

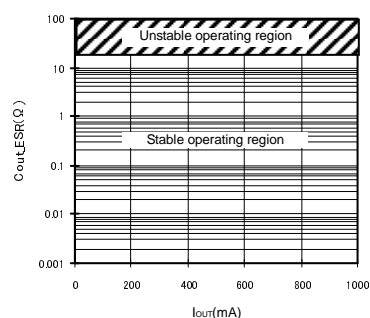
11. Output pin

In order to prevent oscillation, a capacitor needs to be placed between the output pin and GND pin. We recommend a capacitor with a capacitance of more than $1\mu F$ ($3.0V \leq V_{OUT} \leq 15.0V$). Electrolytic, tantalum and ceramic capacitors can be used. We recommend a capacitor with a capacitance of more than $4.7\mu F$ ($1.0V \leq V_{OUT} < 3.0V$). Ceramic capacitors can be used. When selecting the capacitor, ensure that the capacitance of more than $1\mu F$ ($3.0V \leq V_{OUT} \leq 15.0V$) or more than $4.7\mu F$ ($1.0V \leq V_{OUT} < 3.0V$) is maintained at the intended applied voltage and temperature range. Due to changes in temperature, the capacitance can fluctuate possibly resulting in oscillation. For selection of the capacitor, refer to the C_{out_ESR} vs I_{OUT} data. The stable operation range given in the reference data is based on the standalone IC and resistive load. For actual applications, the stable operating range is influenced by the PCB impedance, input supply impedance, and load impedance. Therefore, verification of the final operating environment is needed.

When selecting a ceramic type capacitor, we recommend using X5R, X7R, or better, with excellent temperature and DC-biasing characteristics and high voltage tolerance.

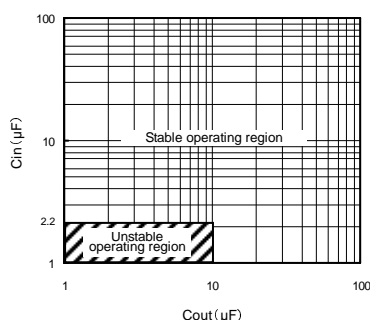
Also, in case of rapidly changing input voltage and load current, select the capacitance in accordance with verifying that the actual application meets the required specification.

$4.0V \leq V_{CC} \leq 26.5V$ $3.0V \leq V_{OUT} \leq 15.0V$
 $-25^\circ C \leq T_a \leq +85^\circ C$
 $5k\Omega \leq R_2 \leq 10k\Omega$ (BD00FC0WEFJ)
 $C_{in} = 2.2\mu F \leq C_{in} \leq 100\mu F$
 $1\mu F \leq C_{out} \leq 100\mu F$



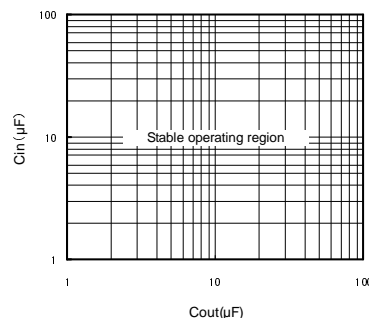
Cout_ESR vs IOUT (reference data)

$4.0V \leq V_{CC} \leq 26.5V$ $3.0V \leq V_{OUT} \leq 15.0V$
 $-25^\circ C \leq T_a \leq +85^\circ C$ $0A \leq I_{OUT} \leq 1A$
 $5k\Omega \leq R_2 \leq 10k\Omega$ (BD00FC0WEFJ)

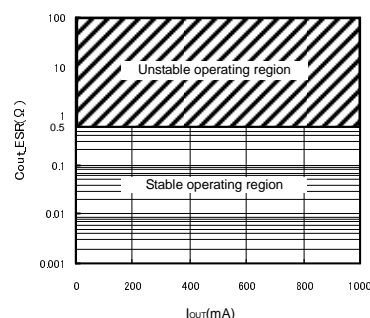


Cin vs Cout (reference data)

$6.0V \leq V_{CC} \leq 26.5V$ $5.0V \leq V_{OUT} \leq 15.0V$
 $-25^\circ C \leq T_a \leq +85^\circ C$ $0A \leq I_{OUT} \leq 1A$
 $5k\Omega \leq R_2 \leq 10k\Omega$ (BD00FC0WEFJ)

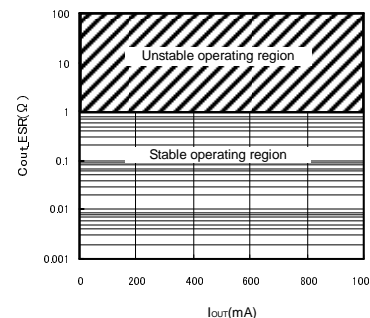


$4.0V \leq V_{CC} \leq 26.5V$
 $1.0V \leq V_{OUT} < 1.5V$
 $-25^\circ C \leq T_a \leq +85^\circ C$
 $5k\Omega \leq R_2 \leq 10k\Omega$ (BD00FC0WEFJ)
 $2.2\mu F \leq C_{in} \leq 100\mu F$
 $4.7\mu F \leq C_{out} \leq 100\mu F$

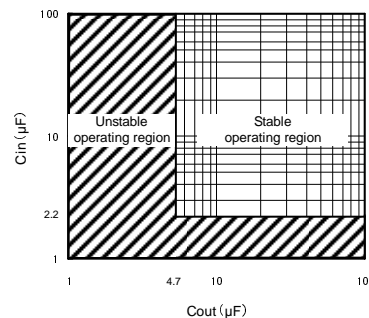


Cout_ESR vs IOUT (reference data)

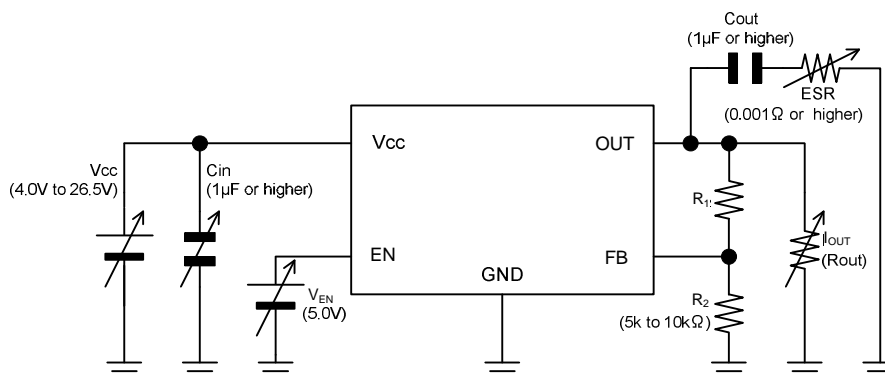
$4.0V \leq V_{CC} \leq 26.5V$
 $1.5V \leq V_{OUT} < 3.0V$
 $-25^\circ C \leq T_a \leq +85^\circ C$
 $5k\Omega \leq R_2 \leq 10k\Omega$ (BD00FC0WEFJ)
 $2.2\mu F \leq C_{in} \leq 100\mu F$
 $4.7\mu F \leq C_{out} \leq 100\mu F$



$4.0V \leq V_{CC} \leq 26.5V$
 $1.0V \leq V_{OUT} < 3.0V$
 $-25^\circ C \leq T_a \leq +85^\circ C$ $0A \leq I_{OUT} \leq 1A$
 $5k\Omega \leq R_2 \leq 10k\Omega$ (BD00FC0WEFJ)



Cin vs Cout (reference data)



※Operation Note 11 Measurement circuit (BD00FC0WEFJ)

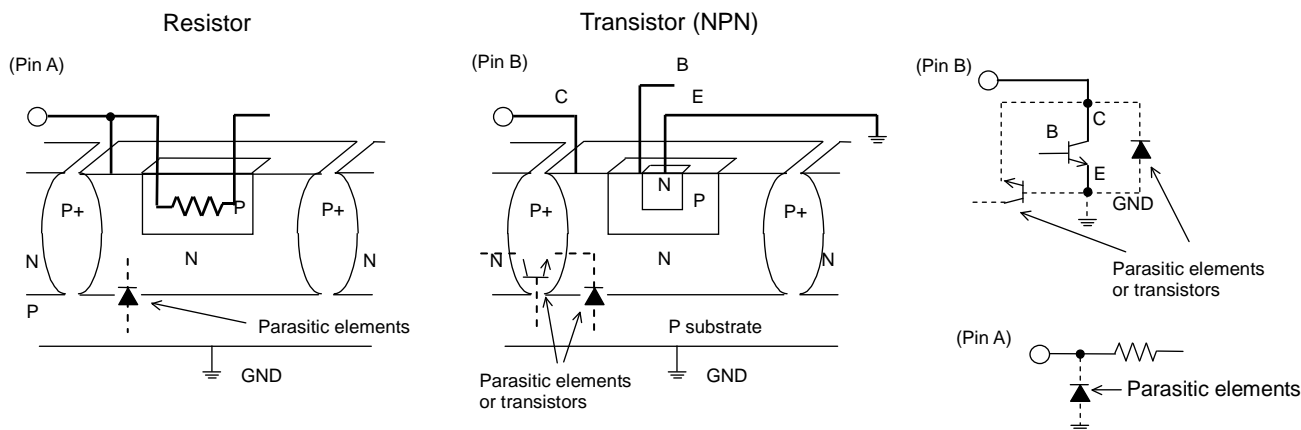
12. EN pin
Do not make the voltage level of the chip's enable pin at floating level or in between $V_{EN(High)}$ and $V_{EN(Low)}$. Otherwise, the output voltage would be unstable or indefinite.
13. For a steep change of the V_{CC} voltage
Because MOSFET for output Transistor is used when an input voltage change is very steep, it may evoke large current. When selecting the value of external circuit constants, please make sure that the operation on the actual application takes these conditions into account.
14. For infinitesimal fluctuations of output voltage.
For applications that have infinitesimal fluctuations of the output voltage caused by some factors (e.g. disturbance noise, input voltage fluctuations, load fluctuations, etc.), please take enough measures to avoid some influence (e.g. insert a filter, etc.).
15. Over current protection circuit (OCP)
The IC incorporates an integrated over-current protection circuit that operates in accordance with the rated output capacity. This circuit serves to protect the IC from damage when the load becomes shorted. It is also designed to limit output current (without latching) in the event of a large and instantaneous current flow from a large capacitor or other component. These protection circuits are effective in preventing damage due to sudden and unexpected accidents. However, the IC should not be used in applications characterized by the continuous or transitive operation of the protection circuits.
16. Thermal Shutdown circuit (TSD)
The IC incorporates a built-in thermal shutdown circuit, which is designed to turn the IC off, completely, in the event of thermal overload. It is not designed to protect the IC from damage or guarantee its operation. IC's should not be used after this function has activated, or in applications where the operation of this circuit is assumed.
17. In some applications, the V_{CC} and the V_{OUT} potential might be reversed, possibly resulting in circuit internal damage or damage to the elements. For example, the accumulated charge in the output pin capacitor flow backward from the V_{OUT} to the V_{CC} when the V_{CC} shorts to the GND. Use a capacitor with a capacitance with less than $1000\mu F$ for reducing the damage. We also recommend using reverse polarity diodes in series between the V_{CC} and the GND or a bypass diode between the V_{OUT} and the V_{CC} .

18. Regarding input pins of the IC

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. PN junctions are formed at the intersection of these P layers with the N layers of other elements, creating parasitic diodes and/or transistors. For example (refer to the Figure below):

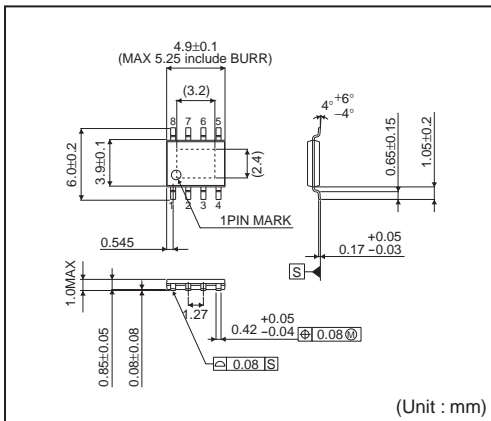
- When $GND > \text{Pin A}$ and $GND > \text{Pin B}$, the PN junction operates as a parasitic diode
- When $GND > \text{Pin B}$, the PN junction operates as a parasitic transistor

Parasitic diodes occur inevitably in the structure of the IC, and the operation of these parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Accordingly, conditions that cause these diodes to operate, such as applying a voltage lower than the GND voltage to an input pin (and thus to the P substrate) should be avoided.



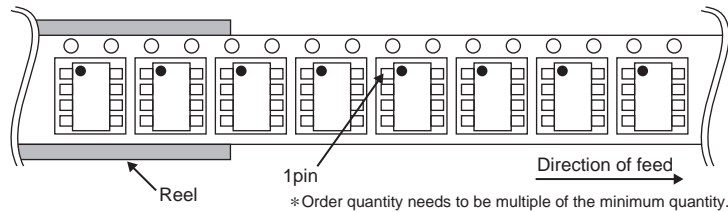
Example of Simple Monolithic IC Architecture

●Physical Dimension Tape and Reel Information

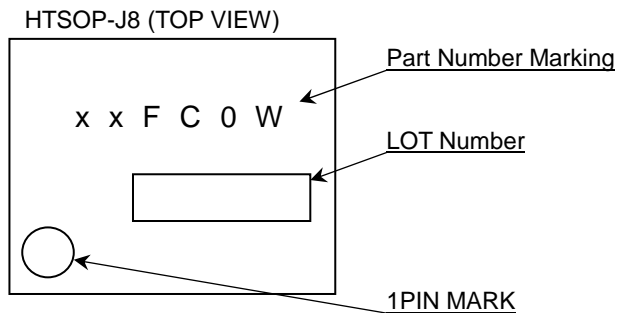
HTSOP-J8

<Tape and Reel information>

Tape	Embossed carrier tape
Quantity	2500pcs
Direction of feed	E2 (The direction is the 1pin of product is at the upper left when you hold reel on the left hand and you pull out the tape on the right hand)



● Marking Diagram



●Revision History

Date	Revision	Changes
27.Aug.2013	001	New Release

Notice

Precaution on using ROHM Products

- Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment ^(Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASS III	CLASS III	CLASS II b	CLASS III
CLASS IV		CLASS III	

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 - Installation of redundant circuits to reduce the impact of single or multiple circuit failure
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 - Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
 - Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - Sealing or coating our Products with resin or other coating materials
 - Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - Use of the Products in places subject to dew condensation
- The Products are not subject to radiation-proof design.
- Please verify and confirm characteristics of the final or mounted products in using the Products.
- In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- In principle, the reflow soldering method must be used; if flow soldering method is preferred, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

Precautions Regarding Application Examples and External Circuits

1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of ionizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

Precaution for Product Label

QR code printed on ROHM Products label is for ROHM's internal use only.

Precaution for Disposition

When disposing Products please dispose them properly using an authorized industry waste company.

Precaution for Foreign Exchange and Foreign Trade act

Since our Products might fall under controlled goods prescribed by the applicable foreign exchange and foreign trade act, please consult with ROHM representative in case of export.

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